

IN THE CLAIMS:

Please cancel claims 1-13 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 14-17 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-13. (Cancelled)

14. (New) A method of forming a 8-layer printed circuit board (PCB) comprising the steps of:

5 preparing a core including a thin compound plate having an inner layer made of a prepreg material and two copper clad layers provided on two outer sides of the inner layer;

performing a circuit formation on the two copper clad layers of the core by way of etching to form two circuit layers on the two outer sides of the inner layer, respectively;

10 forming a laminated dielectric layer from the prepreg material and a copper clad layer are sequentially formed on each of the two circuit layer by way of lamination, so that a four-layer PCB is formed;

forming a circuit on the copper clad layers to form another two circuit layers on outer sides of the two dielectric layers;

15 forming two resin layers being separately formed with a resin build-up process through liquid epoxy coating or dry film type epoxy laminating on the two circuit layers by way of applying a dielectric material and epoxy on outer sides of the two circuit layers;

forming necessary conductive holes on the resin layers by performing laser drilling and mechanical drilling, respectively, to form a PCB;

20 plating the PCB with copper to form a copper-plating layer on all outer surfaces of the PCB;

performing the circuit formation by way of etching the copper-plating layer to form two additional circuit layers; and

25 forming another two laminating dielectric layers from the prepreg material, and another two copper clad layers being sequentially formed on outer sides of the two additional circuit layers by way of lamination to form the 8-layer PCB.

15. (New) The method of claim 14, further comprising performing operations, selected from the group consisting of window formation, laser drilling, plating, and etching,

wherein the operations are performed on the copper clad layers to form other circuit layers on outer sides of the two laminating dielectric layers .

16. (New) The method of claim 15, further comprising performing further operations, selected from the group consisting of applying solder mask, applying plating gold, and spraying tin,

wherein the further operations are performed on the two other circuit layers to complete the eight-layer PCB.

17. (New) The method of claim 14, wherein the prepreg material is a resin-impregnated fiberglass fabric.